

10/594221

Docket No. 8007-1116

IAP01 Rec'd PCT/PTO 25 SEP 2006

PATENT

IN THE U.S. PATENT AND TRADEMARK OFFICE

In re application of

Takashi SUEYOSHI et al.

Conf.

Application No. **NEW NATIONAL PHASE**

Group

Filed September 25, 2006

Examiner

SILICON-CONTAINING CURING COMPOSITION AND HEAT CURED PRODUCT  
THEREOF

**PRELIMINARY AMENDMENT**

Assistant Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

September 25, 2006

Sir:

The following preliminary amendments and remarks are respectfully submitted in connection with the above-identified application.

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begin on page 3 of this paper.

**Remarks** begin on page 5 of this paper.

An **Appendix** is attached following the signature page of this paper.